

SHIGA7.049APC

10/578398
AP20 Rec'd PCT/PTO 04 MAY 2006
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

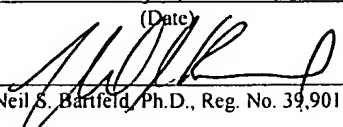
Applicant : Washio et al.
Appl. No. : U.S. National Phase of
PCT/JP2004/017534
Filed : Herewith
For : THICK FILM PHOTORESIST
COMPOSITION AND METHOD
OF FORMING RESIST PATTERN
Examiner : Unassigned
Group Art Unit : Unknown

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

May 4, 2006

(Date)


Neil S. Banfield, Ph.D., Reg. No. 39,901

PRELIMINARY AMENDMENT

Mail Stop PCT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

Prior to examination of the above-referenced application, please enter the following amendments:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims begin on page 3 of this paper.

Remarks begin on page 5 of this paper.